

SUBMINIATURE SOLID STATE LAMP

AM27SYC08 SUPER BRIGHT YELLOW

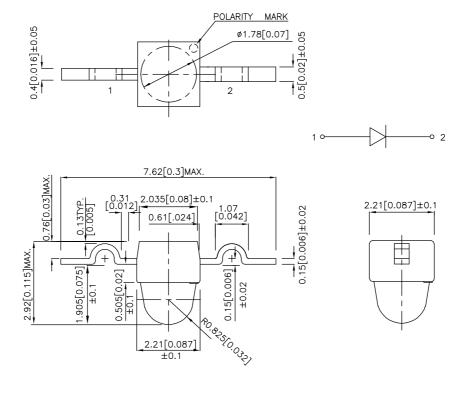
Features

- •SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- •YOKE LEAD.
- •LONG LIFE-SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE: 1000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Super Bright Yellow device is made with DH InGaAIP (on GaAs substrate) light emitting diode chip.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge from the package.4. Specifications are subject to change without notice.

SPEC NO: DSAD1318 **REV NO: V.2** DATE: MAR/10/2005 **PAGE: 1 OF 4** APPROVED: J. Lu CHECKED: Allen Liu DRAWN: S.H.CHEN ERP:1202000408

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min. Typ.		201/2
AM27SYC08	SUPER BRIGHT YELLOW (InGaAIP)	WATER CLEAR	110	700	20°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	IF=20mA
С	Capacitance	Super Bright Yellow	25		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
İR	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Super Bright Yellow	Units	
Power dissipation	125	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

Note

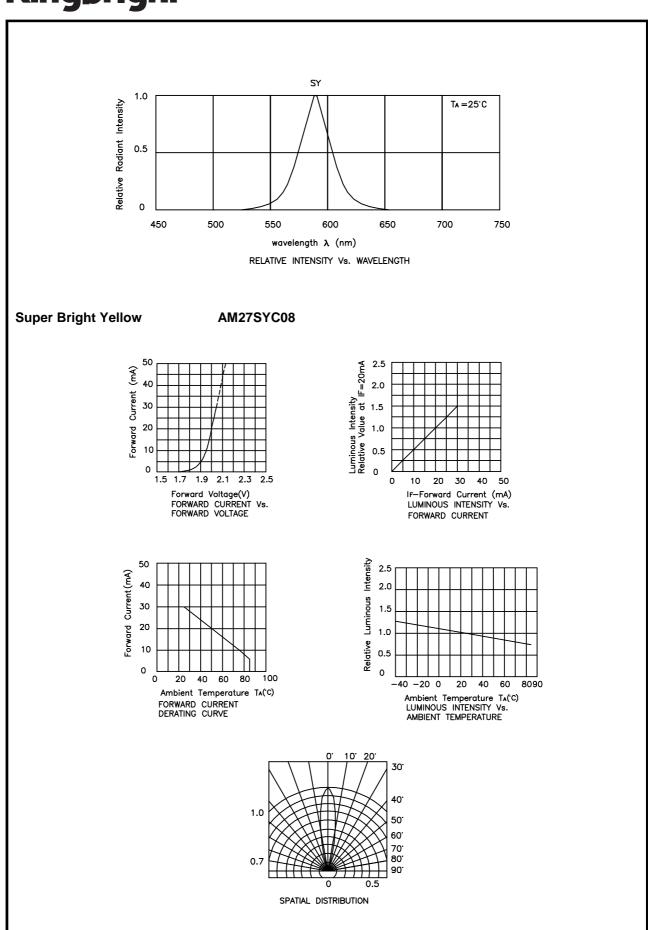
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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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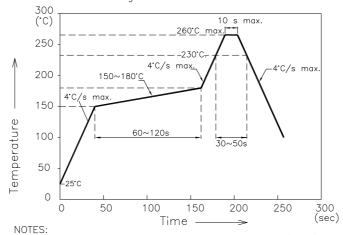
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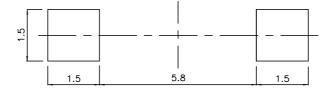
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Reflow Soldering Profile For Lead-free SMT Process.

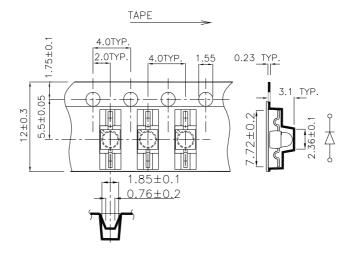


- 1.We recommend the reflow temperature 245°C(±5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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